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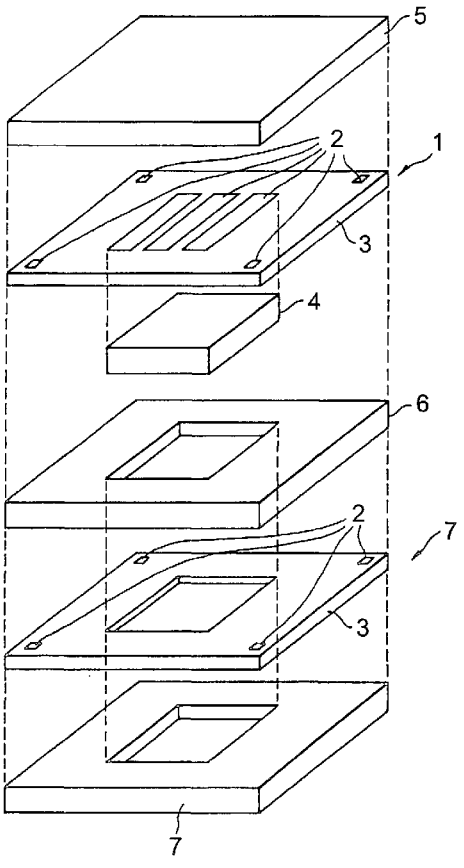
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(54) Title: THERMOSETTING ADHESIVE SHEET WITH ELECTROCONDUCTIVE AND THERMOCONDUCTIVE PROPERTIES



(57) Abstract: A thermosetting adhesive sheet with electroconductive and thermoconductive properties, which comprises a thermosetting adhesive sheet composed of a thermosetting adhesive composition comprising an ethylene-glycidyl (meth)acrylate copolymer and a carboxyl group-containing rosin, where crosslinking is formed between the ethylene of the copolymer by electron beam radiation, and having at least one through-opening region formed at a prescribed location, and further including a low melting point solder placed within said through-opening region(s) formed at the prescribed location(s).

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